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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/088,489	03/26/2002	Tetsuhiro Nakamura	020264	4917
23850	7590	10/14/2003	EXAMINER	
ARMSTRONG, KRATZ, QUINTOS, HANSON & BROOKS, LLP 1725 K STREET, NW SUITE 1000 WASHINGTON, DC 20006			BERRY, RENEE R	
			ART UNIT	PAPER NUMBER
			2818	

DATE MAILED: 10/14/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

# Office Action Summary

Application No.

10/088,489

Applicant(s)

Nakamura

Examiner

Renee Berry

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-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

## Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136 (a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).
- Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

## Status

- 1) ☐ Responsive to communication(s) filed on \_\_\_\_\_
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11; 453 O.G. 213.

## Disposition of Claims

- 4) ☒ Claim(s) 1-22 is/are pending in the application.
- 4a) Of the above, claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☒ Claim(s) 6-8, 10-12, and 22 is/are allowed.
- 6) ☒ Claim(s) 1-5, 9, and 13-21 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claims \_\_\_\_\_ are subject to restriction and/or election requirement.

## Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on \_\_\_\_\_ is/are a) ☐ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
- 11) ☐ The proposed drawing correction filed on \_\_\_\_\_ is: a) ☐ approved b) ☐ disapproved by the Examiner.  
If approved, corrected drawings are required in reply to this Office action.
- 12) ☐ The oath or declaration is objected to by the Examiner.

## Priority under 35 U.S.C. §§ 119 and 120

- 13) ☐ Acknowledgement is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).  
a) ☐ All b) ☐ Some\* c) ☐ None of:  
1. ☐ Certified copies of the priority documents have been received.  
2. ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_  
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).  
\*See the attached detailed Office action for a list of the certified copies not received.
- 14) ☐ Acknowledgement is made of a claim for domestic priority under 35 U.S.C. § 119(e).  
a) ☐ The translation of the foreign language provisional application has been received.
- 15) ☐ Acknowledgement is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121.

## Attachment(s)

- 1) ☒ Notice of References Cited (PTO-892) 4) ☐ Interview Summary (PTO-413) Paper No(s). \_\_\_\_\_
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948) 5) ☐ Notice of Informal Patent Application (PTO-152)
- 3) ☐ Information Disclosure Statement(s) (PTO-1449) Paper No(s). \_\_\_\_\_ 6) ☐ Other:

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## DETAILED ACTION

### *Claim Rejections - 35 USC § 102*

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371© of this title before the invention thereof by the applicant for patent.

The changes made to 35 U.S.C. 102(e) by the American Inventors Protection Act of 1999 (AIPA) do not apply to the examination of this application as the application being examined was not (1) filed on or after November 29, 2000, or (2) voluntarily published under 35 U.S.C. 122(b). Therefore, this application is examined under 35 U.S.C. 102(e) prior to the amendment by the AIPA (pre-AIPA 35 U.S.C. 102(e)).

2. Claims 1, 4, 5, 14-16 and 20 are rejected under 35 U.S.C. 102(e) as being anticipated by US patent no. 6,607,981 to Takahashi et al.

In regard to claim 1, Takahashi teaches an electroless plating method comprising the steps of forming a metallic film made of a metal on which an electroless plating film can be deposited on part of the surface of an object to be plated, or causing the metal to be in contact with part of the surface of the object to be plated, made of a constituent material to which an electroless plating can not be applied; and dipping the object to be plated having a metallic film formed thereon or

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having a metal in contact therewith in an electroless plating bath, and forming an electroless plating film on the surface of the object to be plated, without the metallic film formed thereon and the metal in contact therewith at column 8, lines 40-60, claim 1.

In regard to claim 4, Takahashi teaches an electroless plating method comprising the steps of forming a metallic film made of a metal on which an electroless plating film can be deposited on part of the surface of an object to be plated, or causing the metal to be in contact with part of the surface of the object to be plated, made of constituent material to which an electroless plating can not be applied; and dipping the object to be plated having the metallic film formed thereon or having the metal in contact therewith in an electroless plating bath, wherein the object to be plated is thermoelectric semiconductor at column 8, lines 64-67.

In regard to claim 5, Takahashi teaches an electroless plating film is formed so as to have a dual-layer structure comprised of not less than two metallic films at column 8, lines 64-67.

In regard to claim 14, Takahashi teaches an electroless plating method comprising forming a metallic film made of a metal on which an electroless plating film can be deposited on part of the surface of an object to be plated, or causing the metal to be in contact with part of the surface of the object to be plated, made of a constituent material to which an electroless plating can not be applied; dipping the object to be plated having the metallic film formed thereon or having the metal in contact column 8, lines 40-60, claim 1.

In regard to claim 15, Takahashi teaches preparing an object to be plated; forming a metallic film made of a metal on which electroless plating film can be deposited on part of the

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surface of the object to be plated, or causing the metal to be in contact with part of the surface of the object to be plated; dipping the object to be plated having the metallic film formed thereon or having the metal in contact therewith in an electroless plating bath; and forming an electroless plating film on the entire surface of the object to be plated, except for the insulators column 8, lines 40-60, claim 1.

In regard to claim 16, Takahashi teaches the use is made of a metal or a semiconductor, as the constituent material to which an electroless plating can not be applied at column 4, lines 51-54.

In regard to claim 20, Takahashi teaches use is made of palladium, platinum or nickel as the metal on which the electroless plating film can be deposited at column 2, lines 35-45.

### ***Claim Rejections - 35 USC § 102***

3. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in-

(1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effect under this subsection of a national application published under section 122(b) only if the international application designating the United States was published under Article 21(2)(a) of such treaty in the English language; or

(2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that a patent shall not be deemed filed in the United States for the purposes of this subsection based on the filing of an international application filed under the treaty defined in section 351(a).

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4. Claims 3, 9, 13, and 18 are rejected under 35 U.S.C. 102(e) as being anticipated by US patent no. 6,403,168 to Meyer et al.

In regard to claim 3, Meyer teaches an electroless plating method comprising the steps of forming a metallic film made of a metal on which an electroless plating film can be deposited on part of the surface of an object to be plated, or causing the metal to be in contact with part of the surface of the object to be plated, made of a constituent material to which an electroless plating can not be applied; and dipping the object to be plated having the metallic film formed thereon or having the metal in contact therewith in an electroless plating bath, wherein the object to be plated is made of plural kinds of constituent materials at column 10, lines 5-59, charts.

In regard to claim 9, Meyer teaches an electroless plating method comprising the steps of forming a metallic film made of a metal on which an electroless plating film can be deposited on either an end face or other end face of respective insulation layers, alternately, on the sides of both end faces of a thermoelectric device block formed integrally with a plurality of thermoelectric semiconductors, disposed with the respective insulation layers interposed therebetween, such that the metallic film spans the respective insulation layers and a portion of respective end faces of both the thermoelectric semiconductors adjacent to each other across the respective insulation layers at column 15, lines 9-24, claim 1(a).

In regard to claim 13, Meyer teaches electroless plating method forming a metallic film made of a metal on which an electroless plating film can be deposited on part of the surface of an object to be plated, or causing the metal to be in contact with part of the surface of the object to

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be plated, made of a constituent material to which an electroless plating can not be applied; dipping the object to be plated having the metallic film formed thereon or having the metal in contact therewith in an electroless plating bath, and forming an electroless plating film on the entire surface of the object to be plated, containing the metallic film or the metal; removing the metallic film or the metal, and portions of the electroless plating film, covering up the metallic film or the metal, from the object to be plated; and dipping again the object to be plated subjected to the steps described above in the electroless plating bath at column 16, lines 44-63.

In regard to claim 18, Meyer teaches use is made of a metal or a semiconductor, to which an electroless plating can not be applied, as the constituent material to which an electroless plating can not be applied at column 16, lines 44-63.

*Allowable Subject Matter*

5. Claims 10-12 would be allowable if rewritten to overcome the rejection(s) under 35 U.S.C. 103, set forth in this Office action and to include all of the limitations of the base claim and any intervening claims.
6. Claims 6-8 and 22 are allowed.

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***Conclusion***

7. Any inquiry concerning this communication or earlier communications from the examiner should be directed to R. R. Berry whose telephone number is (703) 305-4544.

*RRB*

RRB

September 30, 2003

*HH*

HOAI HO  
PRIMARY EXAMINER